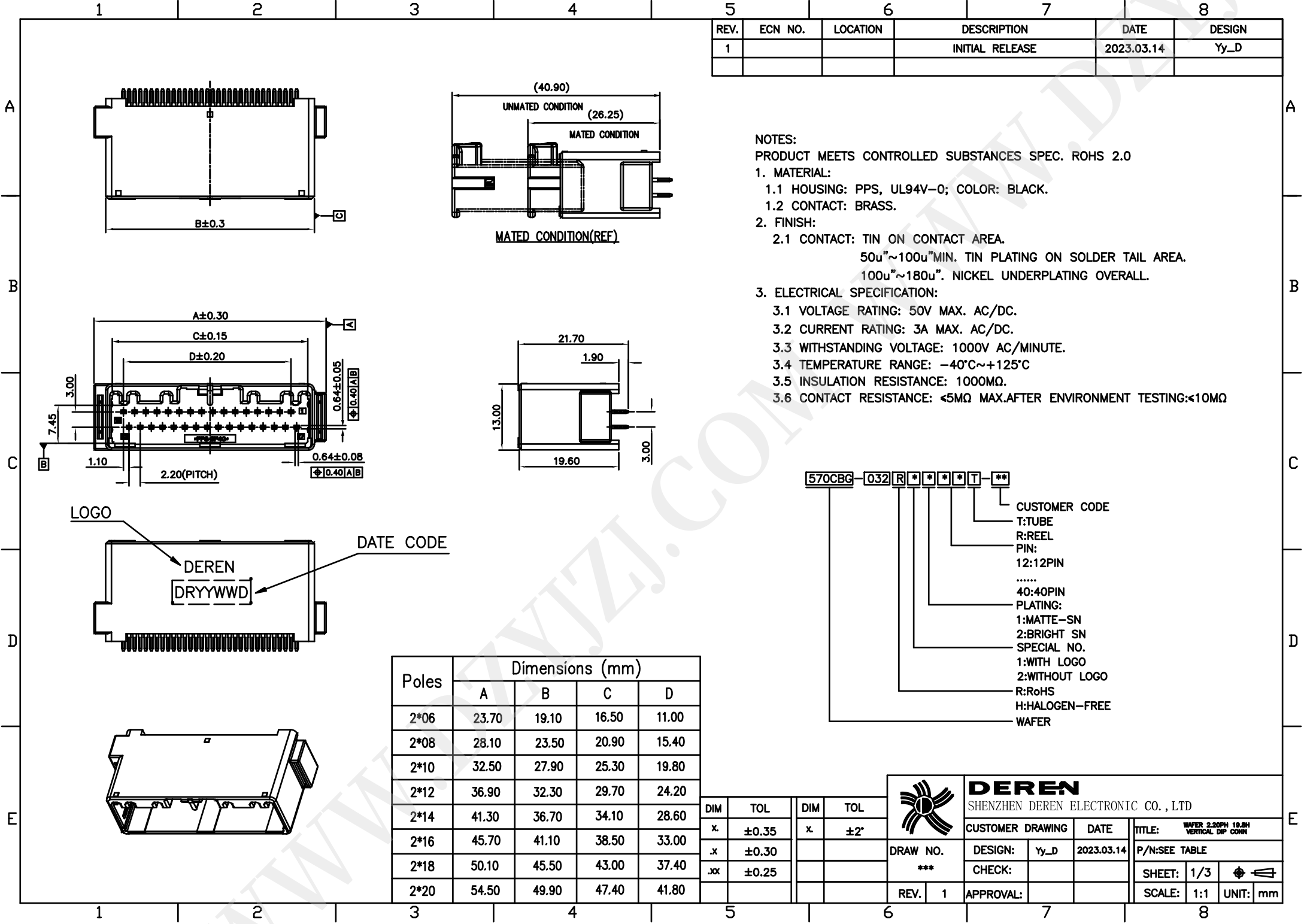




REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
1			INITIAL RELEASE	2023.03.14	Yy_D

- NOTES:
- PRODUCT MEETS CONTROLLED SUBSTANCES SPEC. ROHS 2.0
1. MATERIAL:
- 1.1 HOUSING: PPS, UL94V-0; COLOR: BLACK.
- 1.2 CONTACT: BRASS.
2. FINISH:
- 2.1 CONTACT: TIN ON CONTACT AREA.
- 50u"~100u"MIN. TIN PLATING ON SOLDER TAIL AREA.
- 100u"~180u". NICKEL UNDERPLATING OVERALL.
3. ELECTRICAL SPECIFICATION:
- 3.1 VOLTAGE RATING: 50V MAX. AC/DC.
- 3.2 CURRENT RATING: 3A MAX. AC/DC.
- 3.3 WITHSTANDING VOLTAGE: 1000V AC/MINUTE.
- 3.4 TEMPERATURE RANGE: -40°C~+125°C
- 3.5 INSULATION RESISTANCE: 1000MQ.
- 3.6 CONTACT RESISTANCE: <5MQ MAX.AFTER ENVIRONMENT TESTING:<10MQ

570CBG-032R***T-**

CUSTOMER CODE

T:TUBE

R:REEL

PIN:

12:12PIN

.....

40:40PIN

PLATING:

1:MATTE-SN

2:BRIGHT SN

SPECIAL NO.

1:WITH LOGO

2:WITHOUT LOGO

R:RoHS

H:HALOGEN-FREE

WAFER

Poles	Dimensions (mm)			
	A	B	C	D
2*06	23.70	19.10	16.50	11.00
2*08	28.10	23.50	20.90	15.40
2*10	32.50	27.90	25.30	19.80
2*12	36.90	32.30	29.70	24.20
2*14	41.30	36.70	34.10	28.60
2*16	45.70	41.10	38.50	33.00
2*18	50.10	45.50	43.00	37.40
2*20	54.50	49.90	47.40	41.80

DIM	TOL	DIM	TOL
x	±0.35	x	±2°
.x	±0.30		
.xx	±0.25		

		DEREN					
		SHENZHEN DEREN ELECTRONIC CO., LTD					
DRAW NO. ***		CUSTOMER DRAWING		DATE		TITLE: WAFER 2.20PH 19.8H VERTICAL DIP CONN	
		DESIGN: Yy_D		2023.03.14		P/N:SEE TABLE	
		CHECK:				SHEET: 1/3 	
REV.	1	APPROVAL:				SCALE: 1:1	UNIT: mm

1 2 3 4 5 6 7 8

A

B

C

D

E

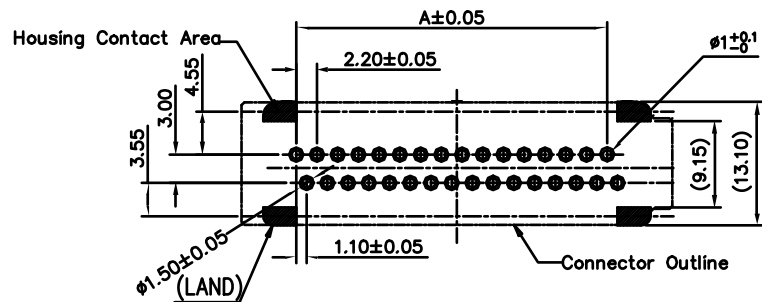
A

B

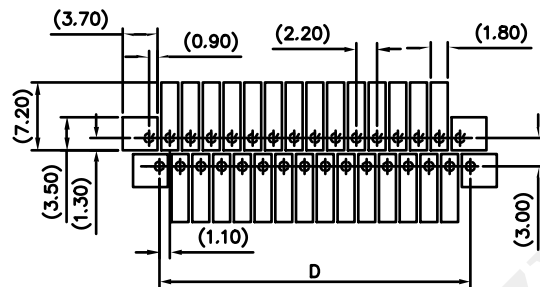
C

D

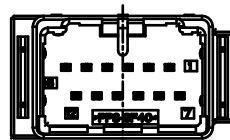
E



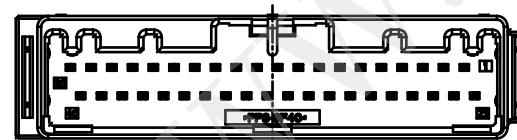
APPLICABLE P.C.B LAYOUT(REF.)
P.C.B THICKNESS t=1.6mm



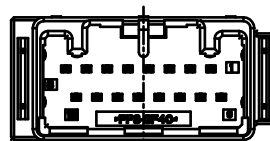
METAL MASK DIMENSIONS(REF.)
MASK THICKNESS T=0.15mm



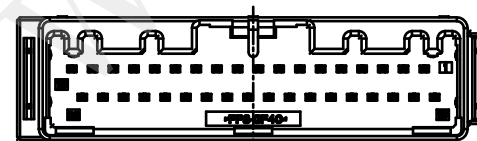
2*06PIN



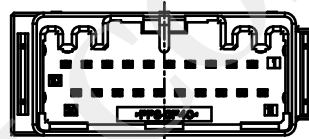
2*20PIN



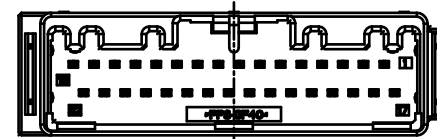
2*08PIN



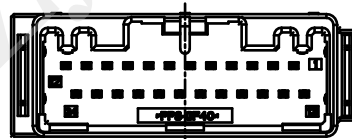
2*18PIN



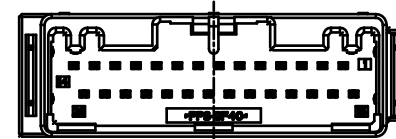
2*10PIN



2*16PIN



2*12PIN

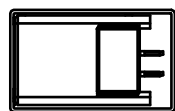
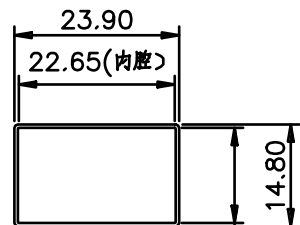


2*14PIN

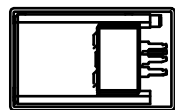
DIM	TOL	DIM	TOL
x	±0.35	x	±2°
.x	±0.30		
.xx	±0.25		

		DEREN	
		SHENZHEN DEREN ELECTRONIC CO., LTD	
DRAW NO.		CUSTOMER DRAWING	DATE
***		DESIGN: yy_D	2023.03.14
REV.		CHECK:	
1		APPROVAL:	
		TITLE:	WAFER 2.20PH 19.2H VERTICAL DIP CONN
		P/N:SEE TABLE	
		SHEET:	2/3
		SCALE:	1:1
		UNIT:	mm

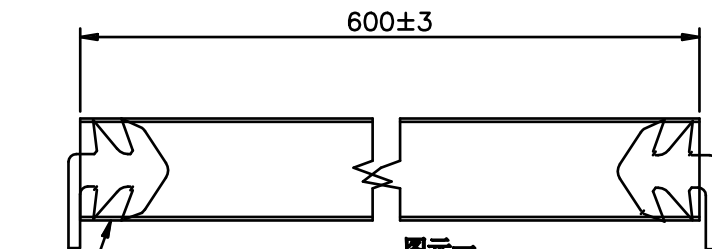
1 2 3 4 5 6 7 8



匹配图不带鱼叉



匹配图带鱼叉



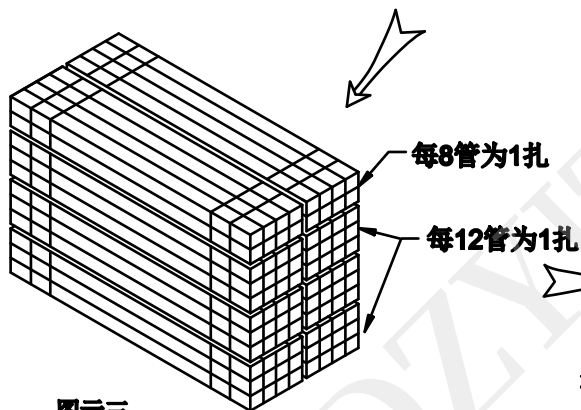
图示一

1.将产品依次装入管中

胶塞

图示二

2.装满产品的管子包扎



图示三

3.将每扎管子包扎

胶带ADHESIVE
TAPE

标签LABEL

图示四

4.装箱, 封胶

说明:

- 1.将产品依图示方向放入真空管内, 方向须一致, 每个真空管放的产品数量依Pin数不同而不同, 具体详见包装明细表, 真空管两头用胶塞塞住, 如图示一。
- 2.将装好产品的真空管平放在桌面上以4PCS为一排然后再叠放3列或2列为1把如图二或图三, 整理好后用PE膜将1把真空管两头PE膜缠绕包好, 并在左边PE膜处贴1PCS产品标签, 如图示二。
- 3.将上步完成的产品以每把进行包扎, 包装成一整扎, 以图示三
- 4.将包扎好产品放入纸箱内, 并将纸箱用胶带封好, 在其侧面右上角贴上出货标签。
- 5.纸箱规格: 600*200*180mm 真空管规格: 600*14.4*14.6mm
- 6.纸箱厚度: 6~7mm

PIN数	每支真空产品 数量PCS/管	每箱真空管数量 PCS管/箱	每箱包装数量 PCS/箱
2*06	24	88	2112
2*08	20	88	1760
2*10	17	88	1496
2*12	15	88	1320
2*14	13	88	1144
2*16	12	88	1056
2*18	11	88	968
2*20	10	88	880

DIM	TOL	DIM	TOL
x		x	
.x			
.xx			



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

CUSTOMER DRAWING		DATE	TITLE: WAFER 2.20PH 19.8H VERTICAL DIP CONN	
DESIGN:	Yy_D	2023.03.14	P/N: SEE TABLE	
CHECK:			SHEET:	3/3
APPROVAL:			SCALE:	N/A UNIT: mm